MICRO-FIT 3.0

						······
Wire-to-Wire B	MI Connecto	or System				
China Contraction of the Contrac	and &		Mate to: IIII		and	
Female Terminal 43030		Receptacle 44133		Male Terminal 43031		Plug 44300
Wire-to-Board	BMI Connect	tor System				
Female Terminal 43030	and d		Mate to: IIII		or	
remaie ierminai 43030		Receptacle 44133		Vertical 44432/45280		Right Angle 44428
	and		Mate to: IIII		or	
Male Terminal 43031		Plug 44300		Vertical 44769		Right Angle 44764
Board-to-Board	BMI Connec	ctor System				
Horizontal Boards						
		Vertical 44769	Mate to: IIII			Vertical 44432/45280
Coplanar Boards						
		Right Angle 44764	Mate to: IIII			Right Angle 44428
Right Angle Boards						
	Mate to: IIII		OR		ate to: IIII	
Vertical 44769		Right Angle 44428		Vertical 44432/45280		Right Angle 44764

MICRO-FIT 3.0 FAMILY APPLICATION EXAMPLES

- Personal Computers ■ Mainframe Computers

- Power Supplies

Order No. USA-106 Rev. 3

Handheld Computers Notebook PCs Fan Tray Assemblies

Americas Headquarters Far East North Headquarters Lisle, Illinois 60532 U.S.A. Yamato, Kanagawa, Japan Tel: 1-800-78MOLEX Tel: 81-462-65-2324 Fax: 630-969-1352 Fax: 81-462-65-2366

Fax Machines

Jurong, Singapore Tel: 65-6-268-6868 Fax: 65-6-265-2985

■ Work Stations

Coffeemakers

Cellular Telephones

AC Power Line Cords

Satellites

Far East South Headquarters

Visit our Web site at http://www.molex.com

European Headquarters Munich, Germany Tel: 49-89-413092-0 Fax: 49-89-401527

Vending Machines

■ Pin Ball Machines

Exercise Equipment ■ Backplane Applications

■ Slot Machines

molex 3.00mm (.118") Pitch

Micro-Fit 3.0[™] Family

Corporate Headquarters 2222 Wellington Ct. Lisle, IL 60532 U.S.A. Tel: 630-969-4550 Fax: 630-969-1352

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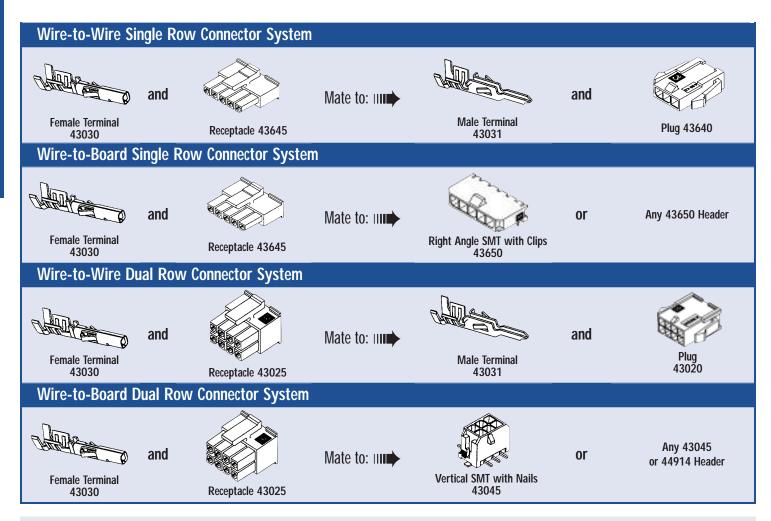
Crimp Terminals										
Description		Order No.		Wire	- Wire Gauge		Plating			
D(Description		Reel	Bag				T luting	
_				3030-0001 3030-0004	43030-0007 43030-0010		0 - 24 0 - 30	-	Tin	
= line		Female Terminal		3030-0004	43030-0010) - 24		15µ" Gold	
Burnell	Female			3030-0005	43030-0011		o - 30	1		
	B		43030-0003		43030-0009	20) - 24		30µ" Gold	
				3030-0006	43030-0012		5 - 30	,	30μ G0IU	
			43031-0001		43031-0007		20 - 24		Tin	
				3031-0004	43031-0010 43031-0008		26 - 30 20 - 24			
	Male 1	[erminal	43031-0002 43031-0005		43031-0008		26 - 30		15µ" Gold	
40		>		3031-0003	43031-0009) - 24		20 0 1	
			43	3031-0006	43031-0012	26	o - 30	1 '	30µ" Gold	
Crimp Housings	;									
	Description	Order		Material		Description	Order I		Material	
R	eceptacles (Use w	ith 43030 ter	minals)			Plugs (Use with	43031 termin	als)		
				Black		Single Row, Free Hanging	43640-X	X01	Black	
	Single Row	43645-X	(X00	Polyester		Single Row,	43640-X	XUU	Polyester	
						Panel Mount	43040-7			
	D 1D	42005)	0,00	Black		Dual Row, Free Hanging	43020-X	X01	Black	
	Dual Row	43025-X	(X00	Polyester	B (2)	Dual Row,	43020-X	XOO	Polyester	
Dialet Assale He					Q L	Panel Mount	13020 //			
Right Angle He	agers									
Single Row	Description	Order No.	Plating	Material	Dual Row	Description	Order No.	Plating	Material	
Carry Carry	Surface Mount — Compatible — with Pegs —	43650-XX00	Tin	High Temperature, Black LCP		Surface Mount Compatible with Pegs	43045-XX00	Tin	High Temperature, Black LCP	
8 JA		43650-XX01	15µ" Gold				43045-XX01	15µ" Gold		
TO E		43650-XX02	30µ" Gold				43045-XX02	30µ" Gold		
1	SMT with Solderable Retention Clip	43650-XX09	Tin	High Temperature, Black LCP		SMT with Solderable Retention Clip	43045-XX06	Tin	High Temperature, Black LCP	
		43650-XX10	15µ" Gold				43045-XX07	15µ" Gold		
		43650-XX11	30µ" Gold				43045-XX08	30µ" Gold		
200		43650-XX12	Tin		Con Contract of the Contract o		43045-XX09	Tin		
	SMT with Solder Tabs	43650-XX13	15µ" Gold	High Temperature, Black LCP		SMT with Solder Tabs	43045-XX10	15µ" Gold	High Temperature, Black LCP	
	Soluel lans	43650-XX14	30µ" Gold	DIACK LUF		Soluti Iabs	43045-XX11	30µ" Gold		
Vertical Headers										
Single Row	Description	Order No.	Plating	Material	Dual Row	Description	Order No.	Plating	Material	
		43650-XX15	Tin			•	43045-XX12	Tin		
Surface Mount Compatible with Pegs		43650-XX16	15µ" Gold	High Temperature, Black LCP		Surface Mount Compatible with Pegs	43045-XX13	15µ" Gold	High Temperature, Black LCP	
		43650-XX17	30µ" Gold				43045-XX14	30µ" Gold		
	SMT with Solderable Retention Clip	43650-XX21	Tin	High Temperature, Black LCP		SMT with Solderable Retention Clip	43045-XX15	Tin	High Temperature, Black LCP	
		43650-XX22	15µ" Gold				43045-XX16	15µ" Gold		
		43650-XX23	30µ" Gold				43045-XX17	30μ" Gold		
u Br		43650-XX24	Tin				43045-XX18	Tin	High Temperature, Black LCP	
	SMT with	43650-XX25	15µ" Gold	High Temperature,		SMT with Solder Tabs	43045-XX19	15µ" Gold		
	Solder Tabs	43650-XX26	30µ" Gold	Black LCP			43045-XX20	30µ" Gold		
		.0000 ///20	25h 2010		STA 2		10 ///20	JULY JOIN		

MICRO-FIT 3.0

Micro-Fit 3.0" Family

Micro-Fit 3.0[™] Family

The Micro-Fit 3.0 is a unique connector system that incorporates many of the features previously found only on large power connectors. These connectors are the perfect choice when you need compact connectors that can carry up to 5.0A of current. Micro-Fit 3.0 is available in circuit sizes 2 to 24 for wire-to-board and wire-to-wire applications. With more than 500 part numbers and still growing, this expansive product line offers through hole and SMT options. SMT versions are available in tape and reel packaging for robotic placement on the PCB.



MICRO-FIT 3.0, CPI AND MICRO-FIT 3.0, BMI CPI

The Micro-Fit 3.0, CPI (Compliant Pin Interface) and Micro-Fit 3.0, BMI CPI (Blind Mate Version with Compliant Pin Interface) are vertical header product extensions featuring press-fit PC tails.

- CPI style (Press-Fit) pins require no soldering to the PCB
- 2.36mm (.093") minimum PCB thickness

Standard CPI								
	Description	Order No.	Plating	Material				
	Standard Vertical CPI	44914-XX01	Tin	High Temperature, Black LCP				
		44914-XX02	12µ" Gold					
		44914-XX03	30μ" Gold					
BMI CPI								
	Blind Mate	45280-XX01	Tin					
	Vertical	45280-XX02	12µ" Gold	High Temperature, Black Glass-Filled Nylon				
	CPI	45280-XX03	30μ" Gold					

MICRO-FIT 3.0, BMI

Micro-Fit 3.0[™] Family

Micro-Fit 3.0, BMI™ (Blind Mate Interface) features an innovative panel mounting design that securely locks the plugs and receptacles in place in the panel cutout, while allowing for removal. The plugs and headers feature a funnel entry to guide the mating receptacle or receptacle header into place. Micro-Fit 3.0, BMI housings and headers mate exclusively with the BMI components shown here.

- Full polarization
- Fully isolated contacts
- Dual row
- Sizes 4 to 24 circuits

- Up to 5.0A per circuit
- Up to 1500V AC dielectric withstand voltage
- UL 94V-0, CSA, TUV approved

Crimp Housings

- Use standard Micro-Fit terminals
- Can be utilized with BMI board-to-board connectors
- Receptacle floats in panel cutout up to 1.27mm (.050") in any direction
 - in Panel thickness: 1.57mm (.062")

	Description	Order No.	Material	
Use with 43030 terminal				
	Panel Mount Receptacle	44133-XX00	Black, Polyester	
Use with 43031 terminal				
	Panel Mount Plug	44300-XX00	Black, Polyester	

Headers

- Can be utilized with BMI wire-to-wire connectors
- Surface mount compatible (SMC)
- 1.57mm (.062") PCB thickness

Black, glass filled nylon housings

Right Angle								
	Description	Order No.	Plating		Description	Order No.	Plating	
	Right Angle Header with Pegs	44428-XX01	Tin		Right Angle Receptacle	44764-XX01	Tin	
		44428-XX02	15µ" Gold			44764-XX02	15μ" Gold	
		44428-XX03	30μ" Gold			44764-XX03	30μ" Gold	
Vertical								
	Vertical Header with Pegs	44432-XX01	Tin		Vertical Receptacle	44769-XX01	Tin	
		44432-XX02	15µ" Gold			44769-XX02	15μ" Gold	
		44432-XX03	30μ" Gold			44769-XX03	30μ" Gold	

Replace XX with number of circuits, 04 to 24